

WHAT IS CLAIMED IS:

1. A guide module for connecting a primary circuit board and a secondary circuit board to a common backplane circuit board, the primary and secondary boards being in a tiered arrangement with both the primary and secondary circuit boards having interface connections on the backplane circuit board, said module comprising:

a body having opposed top and bottom surfaces; and

a locating feature located on one of said body top and bottom surfaces, said locating feature establishing a stack height for the secondary circuit board with respect to the primary circuit board.

2. The guide module of claim 1, wherein said guide module includes a front face, said front face defining a plane that is aligned perpendicular to a mating direction of the primary and secondary boards to the backplane board.

3. The guide module of claim 1, wherein said body includes a front face between said top and bottom surfaces, said front face defining a receptacle for a guide pin on the backplane circuit board.

4. The guide module of claim 1, wherein said locating feature comprises a raised fitting including a centering rib on an outer perimeter thereof, said raised fitting being received in an attachment hole in the secondary circuit board.

5. The guide module of claim 1, wherein said locating feature comprises a raised fitting, said raised fitting including a top surface defining a hole configured to receive a fastener to secure the secondary circuit board to said guide module.

6. The guide module of claim 1, wherein said locating feature comprises a boss having an upper surface, the secondary circuit board resting on said upper surface of

said boss when coupled to the primary circuit board, said upper surface of said boss establishing said stack height.

7. A guide module for connecting a primary circuit board and a secondary circuit board to a common backplane circuit board, the primary and secondary boards being in a tiered arrangement with both said primary and secondary circuit boards having interface connections on the backplane circuit board, said module comprising:

a body including opposed top and bottom surfaces; and

a locating feature located on one of said body top and bottom surfaces, said locating feature defining a stacking plane for the secondary circuit board when the secondary circuit board is coupled to the primary circuit board.

8. The guide module of claim 7, wherein said guide module includes a front face, said front face defining a plane that is aligned perpendicular to a mating direction of the primary and secondary boards to the backplane board.

9. The guide module of claim 7, wherein said body includes a front face between said top and bottom surfaces, said front face defining a receptacle for a guide pin on the backplane circuit board.

10. The guide module of claim 7, wherein said locating feature comprises a raised fitting including a centering rib on an outer perimeter thereof, said raised fitting being received in an attachment hole in the secondary circuit board.

11. The guide module of claim 7, wherein said locating feature comprises a raised fitting, said raised fitting including a top surface defining a hole configured to receive a fastener to secure the secondary circuit board to said guide module.

12. The guide module of claim 7, wherein said locating feature comprises a boss having an upper surface, the secondary circuit board resting on said upper surface

of said boss when coupled to the primary circuit board, said upper surface of said boss defining said stacking plane.

13. A stacked circuit board assembly comprising:

a primary circuit board having an interface for electrically connecting said primary circuit board to a primary circuit board interface on a backplane circuit board;

a secondary circuit board having an interface for electrically connecting said secondary circuit board to a secondary circuit board interface on said backplane circuit board;

a guide module attached to said primary circuit board for mechanically connecting said primary and secondary circuit boards to one another in a tiered arrangement, said guide module providing a common datum for connecting said primary and secondary circuit boards to said backplane circuit board.

14. The assembly of claim 13, wherein said guide module comprises a body including opposed top and bottom surfaces and a locating feature located on one of said body top and bottom surfaces, said locating feature establishing a stack height for the secondary circuit board with respect to the primary circuit board.

15. The assembly of claim 13, wherein said guide module comprises a body including opposed top and bottom surfaces, and a locating feature located on one of said body top and bottom surfaces, said locating feature defining a stacking plane for the secondary circuit board when the secondary circuit board is coupled to the primary circuit board.

16. The guide module of claim 13, wherein said guide module includes a front face, said front face defining a plane that is aligned perpendicular to a mating direction of the primary and secondary boards to the backplane board.

17. The guide module of claim 13, wherein said body includes a front face between said top and bottom surfaces, said front face defining a receptacle for a guide pin on the backplane circuit board.

18. The guide module of claim 13, wherein said guide module comprises a body including opposed top and bottom surfaces, and a locating feature located on one of said body top and bottom surfaces, and wherein said locating feature comprises:

a raised fitting including a centering rib on an outer perimeter thereof, said raised fitting being received in an attachment hole in the secondary circuit board, said raised fitting further including a top surface defining a hole configured to receive a fastener to secure the secondary circuit board to said guide module; and

a boss located at a base of said raised fitting, said boss having an upper surface, the secondary circuit board resting on said upper surface of said boss when coupled to the primary circuit board, said upper surface of said boss determining a stack height for said secondary board with respect to said primary circuit board and defining a stacking plane for said secondary circuit board.

19. The guide module of claim 13, wherein said guide module comprises a body including opposed top and bottom surfaces, and a locating feature located on one of said body top and bottom surfaces, and wherein said locating feature comprises:

a raised fitting including a centering rib on an outer perimeter thereof, said raised fitting being received in an attachment hole in the secondary circuit board, said raised fitting further including a top surface defining a hole configured to receive a fastener to secure the secondary circuit board to said guide module; and

a boss located at a base of said raised fitting and substantially concentric therewith, the secondary circuit board resting on an upper surface of said boss when

coupled to the primary circuit board, said boss and said fitting being molded with said module.